

Hyperfast Rectifier, 8 A FRED Pt®





DPAK (TO-252AA)

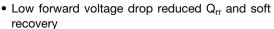
LINKS TO ADDITIONAL RESOURCES



PRIMARY CHARACTERISTICS							
I _{F(AV)} 8 A							
V _R	200 V						
V _F at I _F	0.75 V						
t _{rr} (typ.)	23 ns						
T _J max.	175 °C						
Package	DPAK (TO-252AA)						
Circuit configuration	Single						

FEATURES

- Hyperfast recovery time
- 175 °C max. operating junction temperature
- Output rectification freewheeling





- Low leakage current
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Material categorization: for definitions of compliance please see <u>www.vishav.com/doc?99912</u>

DESCRIPTION / APPLICATIONS

State of the art hyperfast recovery rectifiers specifically designed with optimized performance of forward voltage drop and hyperfast recovery time. The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in the output rectification stage of SMPS, UPS, DC/DC converters as well as freewheeling diode in low voltage inverters and chopper motor drives.

Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

MECHANICAL DATA

Case: DPAK (TO-252AA)

Molding compound meets UL 94 V-0 flammability rating **Terminals:** matte tin plated leads, solderable per J-STD-002

ABSOLUTE MAXIMUM RATINGS							
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS			
Peak repetitive reverse voltage	V _{RRM}		200	V			
Average rectified forward current	I _{F(AV)}	T _C = 156 °C	8				
Non-repetitive peak surge current	I _{FSM}	T _J = 25 °C	140	Α			
Peak repetitive forward current	I _{FM}	T _C = 156 °C, f = 20 kHz, d = 50 %	16				
Operating junction and storage temperatures	T _J , T _{Stg}		-65 to +175	°C			

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Breakdown voltage, blocking voltage	V_{BR} , V_{R}	I _R = 100 μA	200	-	-		
Face and allows	V _F	I _F = 8 A	-	0.91	0.97	V	
Forward voltage		I _F = 8 A, T _J = 150 °C	-	0.75	0.85		
Devene leeken euwent	I _R	$V_R = V_R$ rated	-	-	5		
Reverse leakage current		$T_J = 150 ^{\circ}\text{C}, V_R = V_R \text{rated}$	-	6	60	μA	
Junction capacitance	C _T	V _R = 200 V	-	22	-	pF	
Series inductance	L _S	Measured lead to lead 5 mm from package body	-	8	-	nH	



DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)									
PARAMETER	SYMBOL	TEST CO	MIN.	TYP.	MAX.	UNITS			
		$I_F = 1.0 \text{ A}, dI_F/dt =$	100 A/ μ s, $V_R = 30 V$	ı	23	27			
Reverse recovery time		$I_F = 1.0 \text{ A}, dI_F/dt = 50 \text{ A/}\mu\text{s}, V_R = 30 \text{ V}$		-	27	-			
neverse recovery time	t _{rr}	T _J = 25 °C		-	24	-	ns -		
		T _J = 125 °C		-	33	-			
Dook rooms ourrent	ı	T _J = 25 °C	· .	-	2.3	-	Α		
Peak recovery current	I _{RRM}	IRRM	T _J = 125 °C	dI _F /dt = 200 A/μs V _R = 160 V	-	4.3	-	A	
Dougrap resource charge	0	T _J = 25 °C	VR = 100 V	-	27	-	nC		
Reverse recovery charge	Q _{rr}	T _J = 125 °C		i	70	-	110		

THERMAL - MECHANICAL SPECIFICATIONS							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Maximum junction and storage temperature range	T _J , T _{Stg}		-65	-	175	°C	
Thermal resistance, junction to case per leg	R _{thJC}		-	1.7	2.5	°C/W	
Approximate weight				0.3		g	
Marking device		Case style D-PAK (TO-252AA)		8EWH	H02FN		

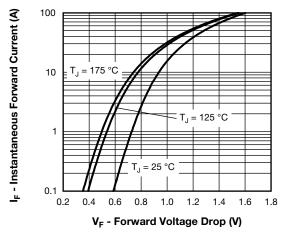


Fig. 1 - Typical Forward Voltage Drop Characteristics

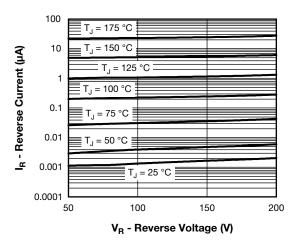


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

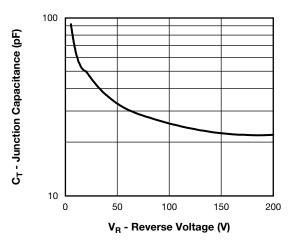


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

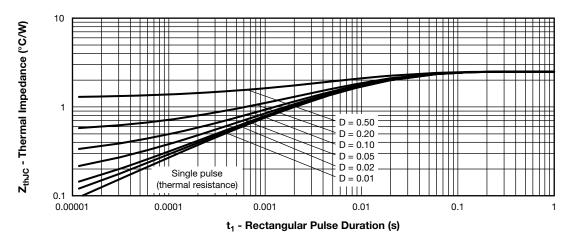


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

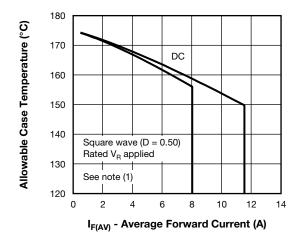


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

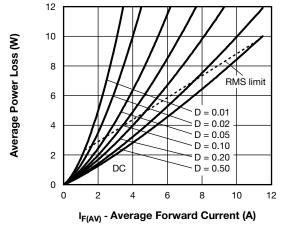


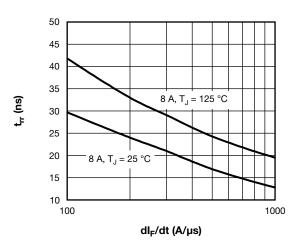
Fig. 6 - Forward Power Loss Characteristics

Note

⁽¹⁾ Formula used: T_C = T_J - (Pd + Pd_{REV}) x R_{thJC}; Pd = forward power loss = I_{F(AV)} x V_{FM} at (I_{F(AV)}/D) (see fig. 6); Pd_{REV} = inverse power loss = V_{R1} x I_R (1 - D); I_R at V_{R1} = rated V_R

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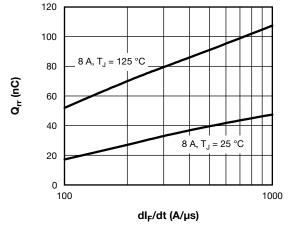


Fig. 7 - Typical Reverse Recovery Time vs. dl_F/dt

Fig. 8 - Typical Stored Charge vs. dl_F/dt

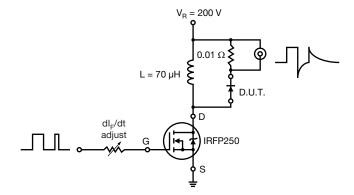
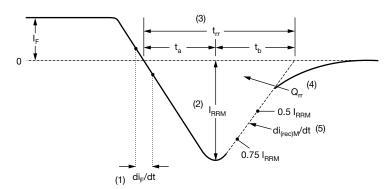


Fig. 9 - Reverse Recovery Parameter Test Circuit



- (1) di_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- (3) t_{rr} reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through 0.75 I_{RBM} and 0.50 I_{RBM} extrapolated to zero current.
- (4) Q_{rr} area under curve defined by t_{rr} and I_{RRM}

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

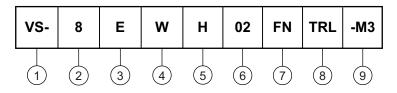
(5) $di_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}

Fig. 10 - Reverse Recovery Waveform and Definitions



ORDERING INFORMATION TABLE





1 - Vishay Semiconductors product

2 - Current rating (8 = 8 A)

Circuit configuration:

E = single diode

4 - Package identifier:

W = D-PAK

H = hyperfast recovery

6 - Voltage rating (02 = 200 V)

7 - FN = TO-252AA

8 - • None = tube

• TR = tape and reel

• TRL = tape and reel (left oriented)

• TRR = tape and reel (right oriented)

9 - Environmental digit:

-M3 = halogen-free, RoHS-compliant and terminations lead (Pb)-free

ORDERING INFORMATION (Example)							
PREFERRED P/N	BASE QUANTITY	PACKAGING DESCRIPTION					
VS-8EWH02FN-M3	75	Antistatic plastic tube					
VS-8EWH02FNTR-M3	2000	13" diameter reel					
VS-8EWH02FNTRL-M3	3000	13" diameter reel					
VS-8EWH02FNTRR-M3	3000	13" diameter reel					

LINKS TO RELATED DOCUMENTS					
Dimensions	www.vishay.com/doc?95627				
Part marking information	www.vishay.com/doc?95176				
Packaging information	www.vishay.com/doc?95033				
SPICE model	www.vishay.com/doc?96997				



D-PAK (TO-252AA) "M"

DIMENSIONS in millimeters and inches



SYMBOL	MILLIN	IETERS	INCHES		NOTES
STIVIDOL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	2.18	2.39	0.086	0.094	
A1	-	0.13	-	0.005	
b	0.64	0.89	0.025	0.035	
b2	0.76	1.14	0.030	0.045	
b3	4.95	5.46	0.195	0.215	3
С	0.46	0.61	0.018	0.024	
c2	0.46	0.89	0.018	0.035	
D	5.97	6.22	0.235	0.245	5
D1	5.21	-	0.205	-	3
Е	6.35	6.73	0.250	0.265	5
E1	4.32	-	0.170	-	3

SYMBOL	MILLIN	IETERS	INCHES		NOTES
STWIBOL	MIN.	MAX.	MIN.	MAX.	NOTES
е	2.29	BSC	0.090	BSC	
Н	9.40	10.41	0.370	0.410	
L	1.40	1.78	0.055	0.070	
L1	2.74 BSC		0.108 REF.		
L2	0.51	BSC	0.020 BSC		
L3	0.89	1.27	0.035	0.050	3
L4	-	1.02	-	0.040	
L5	1.14	1.52	0.045	0.060	2
Ø	0°	10°	0°	10°	
Ø1	0°	15°	0°	15°	
Ø2	25°	35°	25°	35°	

Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension uncontrolled in L5
- (3) Dimension D1, E1, L3 and b3 establish a minimum mounting surface for thermal pad
- (4) Section C C dimension apply to the flat section of the lead between 0.13 and 0.25 mm (0.005 and 0.10") from the lead tip
- (5) Dimension D, and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (6) Dimension b1 and c1 applied to base metal only
- (7) Datum A and B to be determined at datum plane H
- (8) Outline conforms to JEDEC® outline TO-252AA



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